Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .006” Diameter**

**Backside Potential: Cathode**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .017” X .017” DATE: 9/2/21**

**MFG: NATIONAL SEMI THICKNESS .008” P/N: 1N3595**

**DG 10.1.2**

#### Rev B, 7/19/02